

# **Digital Media**

## **Code Information**

- **MOS**
- **Linear-IC**
- **SIP**

**August 2009**

# MOS Code Information(1/2)

Last Updated : August 2009

**S** **5** X X X X X X X X - X X X X  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

## 1. System LSI (S)

## 2. Large Classification : MOS (5)

### 3. Small Classification

- A : Audio
- B : Analog Core
- C : Camera
- D : Display
- F : CCD
- G : General
- H : Home(Appliance) Video
- I : Digital Core
- K : CIS
- L : Optical
- M : Mobile Automation
- N : Network
- P : Processor
- S : SLINK(Serial Link)
- T : Telecom
- V : Process Vehicle
- W : Library
- X : MODULE(CAMERA MODULE)
- Y : Memory Card
- Z : Custom
- 2 : EEPROM
- 4 : DRAM CORE
- 6 : FLASH CORE

### 4~7.

Serial No

### 8. Version

A~Z

\*1st Version → X

## 9~10. Mask Option

11. " - "

### 12. Package Type

- |           |              |
|-----------|--------------|
| 1 : TEBGA | 2 : MODULE   |
| 3 : QFN   | 4 : MLF      |
| 5 : ELP2  | 6 : WFP      |
| 7 : LPCC  | 8 : FCBGA    |
| 9 : PBGA  | A : SDIP     |
| B : BGA   | C : CHIP BIZ |
| D : DIP   | E : LQFP     |
| F : BCC++ | G : ELQFP    |
| H : ULGA  | J : ELP      |
| K : SBGA  | L : FCFBGA   |
| M : QFPH  | N : PBGAH    |
| P : PLCC  | Q : QFP      |
| R : TSSOP | S : SOP      |
| T : TQFP  | U : UELP     |
| V : SSOP  | W : WAFER    |
| X : ETQFP | Y : FBGA     |
| Z : STBGA |              |

### 13. Reserved

- |                  |                  |
|------------------|------------------|
| 0 : none         | 1 : PKG Option 1 |
| 2 : PKG Option 2 | 3 : PKG Option 3 |
| .....            |                  |
| G : PKG Option G | H : PKG Option H |

### 14. Packing

- |                                    |                 |
|------------------------------------|-----------------|
| B : Tube                           | U : Bulk        |
| R : Tray                           | T : Tape & Reel |
| S : Tape & Reel Reverse            | C : Chip Biz    |
| D : Chip Biz (3 Inch tray)         |                 |
| E : Chip Biz (4 Inch tray)         |                 |
| F : Chip Biz (Reverse)             |                 |
| W : WF Biz Draft Wafer             |                 |
| X : WF Biz Full Cutting            |                 |
| 3 : Tape & Reel (Halogen-Free PKG) |                 |
| 4 : Tray (Halogen-Free PKG)        |                 |
| 5 : Tube (Halogen-Free PKG)        |                 |
| 7 : Tape & Reel (Lead-Free PKG)    |                 |
| 8 : Tray (Lead-Free PKG)           |                 |
| 9 : Tube (Lead-Free PKG)           |                 |

# MOS Code Information(2/2)

Last Updated : August 2009

<u>S</u>	<u>5</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>-</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15

## 15. Customer

- 0 : None
- 1 : Bonding Option 1
- 2 : Bonding Option 2
- 3 : Bonding Option 3
- 4 : Bonding Option 4
- 5 : Bonding Option 5
- 6 : Bonding Option 6
- 7 : Bonding Option 7
- 8 : Bonding Option 8
- 9 : Bonding Option 9
- A : Special Marking 1
- B : Special Marking 2
- C : Special Marking 3
- D : Special Marking 4
- E : Special Marking 5
- F : Special Marking 6
- K : Reliability Test
- L : No Logo
- M : No Marking
- N : ANAM Assembly
- Q : Bonding Option 10
- R : Bonding Option 11
- S : Bonding Option 12
- T : Bonding Option 13
- U : Bonding Option 14
- Z : Customer Option

# L(Linear)-IC Code Information

Last Updated : August 2009

**S** **1** X X X X X X X X - X X X X  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

## 1. System LSI (S)

## 2. Large Classification : L-IC (1)

## 3. Small Classification

- A : Analog Audio
- C : Camera
- D : Display
- G : General
- H : Home(Appliance) Video
- L : Optical
- M : Mobile Communication
- N : Network
- P : PC Peripheral
- S : Smart Power
- T : Telecom
- V : Processor Vehicle
- Z : Custom

## 4~7.

Serial No

## 8. Version

A~Z

\*1st Version → X

## 9~10. Mask Option

## 11. " - "

## 12. Package Type

- |           |           |
|-----------|-----------|
| 2 : LPCC  | 3 : SOPH  |
| 4 : WFP   | A : SDIP  |
| B : BCC+  | D : DIP   |
| E : LQFP  | F : BCC   |
| G : CLCC  | H : DIPH  |
| I : SIP   | J : ELP2  |
| M : MLF   | N : QFN   |
| P : ELP   | Q : QFP   |
| R : TSSOP | S : SOP   |
| T : TQFP  | V : SSOP  |
| W : WAFER | X : SIPH  |
| Y : FBGA  | Z : BCC++ |

## 13. Reserved

### - Bin Grade

- 0 : None or Root Product
- A : 1st derivative Product
- B : 2nd derivative Product

### - PKG Option

- 1 : PKG Option 1
- 2 : PKG Option 2
- 3 : PKG Option 3

## 14. Packing

- |                                    |                 |
|------------------------------------|-----------------|
| B : Tube                           | U : Bulk        |
| R : Tray                           | T : Tape & Reel |
| S : Tape & Reel Reverse            | C : Chip Biz    |
| D : Chip Biz (3 Inch tray)         |                 |
| E : Chip Biz (4 Inch tray)         |                 |
| F : Chip Biz (Reverse)             |                 |
| W : WF Biz Draft Wafer             |                 |
| X : WF Biz Full Cutting            |                 |
| 3 : Tape & Reel (Halogen-Free PKG) |                 |
| 4 : Tray (Halogen-Free PKG)        |                 |
| 5 : Tube (Halogen-Free PKG)        |                 |
| 7 : Tape & Reel (Lead-Free PKG)    |                 |
| 8 : Tray (Lead-Free PKG)           |                 |
| 9 : Tube (Lead-Free PKG)           |                 |

## 15. Customer

- |                       |                       |
|-----------------------|-----------------------|
| 0 : None              | 2 : Bonding Option 2  |
| 1 : Bonding Option 1  | 4 : Bonding Option 4  |
| 3 : Bonding Option 3  | 6 : Bonding Option 6  |
| 5 : Bonding Option 5  | 8 : Bonding Option 8  |
| 7 : Bonding Option 7  | A : Special Marking 1 |
| 9 : Bonding Option 9  | C : Special Marking 3 |
| B : Special Marking 2 | E : Special Marking 5 |
| D : Special Marking 4 | K : Reliability Test  |
| F : Special Marking 6 | M : No Marking        |
| L : No Logo           | Q : Bonding Option 10 |
| N : ANAM Assembly     | S : Bonding Option 12 |
| R : Bonding Option 11 | U : Bonding Option 14 |
| T : Bonding Option 13 |                       |
| Z : Customer Option   |                       |

# SIP I Code Information

Last Updated : August 2009

<u>S</u>	<u>A</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	-	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15

## 1. System LSI (S)

## 2. Large Classification : SIP I (A)

In the case of SIP products including S1/S3/S5 products

## 3. Small Classification

- 1. Linear IC
- 3 : Microcontroller
- 5 : MOS

## 4~7.

Serial No

## 8. Version

A~Z

\*1st Version → X

## 9~10. Mask Option

## 11. " - "

## 12. Package Type (AG01000 is standard)

N : COB	M : MSP
Y : FBGA	U : LGA

## 13. Reserved

- 0 : The Final assembly
- 1 : Initial assembly

## 14. Packing

- |                                    |                 |
|------------------------------------|-----------------|
| B : Tube                           | U : Bulk        |
| R : Tray                           | T : Tape & Reel |
| S : Tape & Reel Reverse            | C : Chip Biz    |
| D : Chip Biz (3 Inch tray)         |                 |
| E : Chip Biz (4 Inch tray)         |                 |
| F : Chip Biz (Reverse)             |                 |
| W : WF Biz Draft Wafer             |                 |
| X : WF Biz Full Cutting            |                 |
| 3 : Tape & Reel (Halogen-Free PKG) |                 |
| 4 : Tray (Halogen-Free PKG)        |                 |
| 5 : Tube (Halogen-Free PKG)        |                 |
| 7 : Tape & Reel (Lead-Free PKG)    |                 |
| 8 : Tray (Lead-Free PKG)           |                 |
| 9 : Tube (Lead-Free PKG)           |                 |

## 15. Reserved

- 0 : Reserved

# SIP II Code Information

Last Updated : August 2009

<u>S</u>	<u>B</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	-	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15

## 1. System LSI (S)

## 2. Large Classification : SIP II (B)

In the case of SIP products including of S4/S7 products

## 3. Small Classification

4 : ASIC

## 4~7.

Serial No

## 8. Version

A~Z

\*1st Version → X

## 9~10. Mask Option

11. " - "

## 12. Package Type (AG01000 is standard)

A : BGAH

B : BGA

E : LQFP

Y : FBGA

U : LGA

## 13. Reserved

0 : The Final assembly

1 : Initial assembly

2 : Second assembly

## 14. Packing

B : Tube

U : Bulk

R : Tray

T : Tape & Reel

S : Tape & Reel Reverse

C : Chip Biz

D : Chip Biz (3 Inch tray)

E : Chip Biz (4 Inch tray)

F : Chip Biz (Reverse)

W : WF Biz Draft Wafer

X : WF Biz Full Cutting

3 : Tape & Reel (Halogen-Free PKG)

4 : Tray (Halogen-Free PKG)

5 : Tube (Halogen-Free PKG)

7 : Tape & Reel (Lead-Free PKG)

8 : Tray (Lead-Free PKG)

9 : Tube (Lead-Free PKG)

## 15. Reserved

0 : Reserved